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 Parallel-to-Serial, Serial-to-Parallel Conversions 	DW OR N PACKAGE (TOP VIEW)
Left or Right Shifts	
 Parallel Synchronous Loading 	
Direct Overriding Clear	Q _A [] 2 19 [] S1 Q _B [] 3 18 [] A
 Temporary Data Latching Capability 	GND [] 4 17] B
 Flow-Through Architecture to Optimize 	GND 🛛 5 16 🗍 V _{CC}
PCB Layout	GND [] 6 15 [] V _{CC}
 Center-Pin V_{CC} and GND Configurations to 	
Minimize High-Speed Switching Noise	
 EPIC[™] (Enhanced-Performance Implanted 	
CMOS) 1-μm Process	
500 mA Typical Latah Un Immunity at	

- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages, and Standard Plastic 300-mil DIPs

description

This bidirectional shift register features parallel outputs, right-shift and left-shift serial inputs, operating-mode-control inputs, and a direct overriding clear line. The register has four distinct modes of operation:

Parallel (broadside) load Shift right (in the direction Q_A toward Q_D) Shift left (in the direction Q_D toward Q_A) Inhibit clocking (do nothing).

Synchronous parallel loading is accomplished by applying the 4 bits of data and taking both mode control inputs, S0 and S1, high. The data are loaded into the associated flip-flops and appear at the outputs after the positive transition of the clock input. During loading, serial data flow is inhibited.

Shift right is accomplished synchronously with the rising edge of the clock pulse when S0 is high and S1 is low. Serial data for this mode is entered at the shift-right data input. When S0 is low and S1 is high, data shifts left synchronously, and new data is entered at the shift-left serial inputs. Clocking of the flip-flop is inhibited when both mode control inputs are low.

The 74AC11194 is characterized for operation from – 40°C to 85°C.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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	Function Table												
	INPUTS										OUTI	PUTS	
CLEAR	MO	DE	CLOCK	SEF	RIAL		PARA	LLEL		0.	0-	0.5	0
CLEAR	S1	S0	CLUCK	LEFT	RIGHT	Α	В	С	D	QA	QB	۵C	QD
L	Х	Х	Х	Х	Х	Х	Х	Х	Х	L	L	L	L
н	Х	Х	L	Х	Х	Х	Х	Х	Х	Q _{A0}	Q_{B0}	Q _{C0}	Q _{D0}
н	н	Н	\uparrow	Х	Х	а	b	С	d	а	b	С	d
н	L	Н	↑	Х	Н	Х	Х	Х	Х	Н	Q _{An}	Q _{Bn}	QCn
н	L	Н	↑	Х	L	Х	Х	Х	Х	L	Q _{An}	Q _{Bn}	QCn
н	н	L	↑	Н	Х	Х	Х	Х	Х	Q _{Bn}	QCn	Q _{Dn}	Н
н	Н	L	↑	L	Х	Х	Х	Х	Х	Q _{Bn}	QCn	Q _{Dn}	L
Н	L	L	Х	Х	Х	Х	Х	Х	Х	Q _{AO}	Q _{BO}	QCO	Q _{DO}

H = high level (steady state)

L = low level (steady state)

X = irrelevant (any input, including transitions)

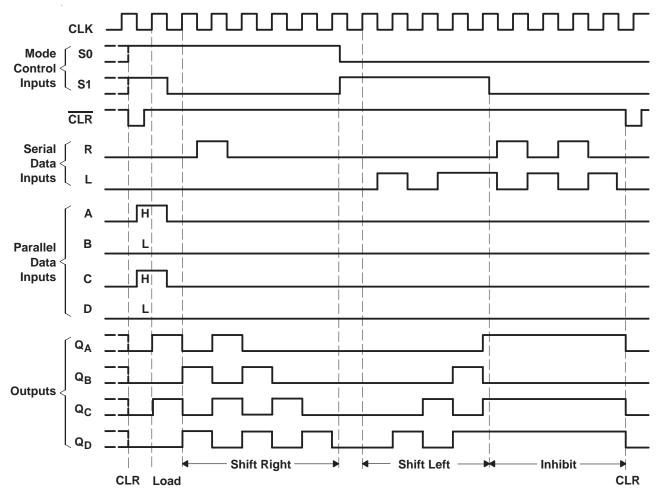
 \uparrow = transition from low to high level

a,b,c,d = the level of steady-state input at inputs A, B, C, or D, respectively.

 Q_{AO} , Q_{BO} , Q_{CO} , Q_{DO} = the level of Q_A , Q_B , Q_C , or Q_D , respectively, before the indicated steady-state input conditions were established.

 Q_{An} , Q_{Bn} , Q_{Cn} , Q_{Dn} = the level of Q_A , Q_B , Q_C , or Q_D respectively, before the most-recent \uparrow transition of the clock.

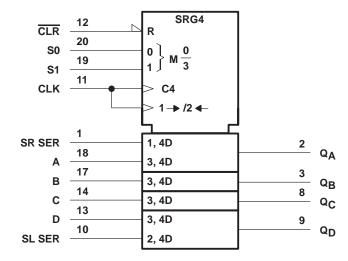
timing clear, load, right-shift, inhibit, and clear sequences



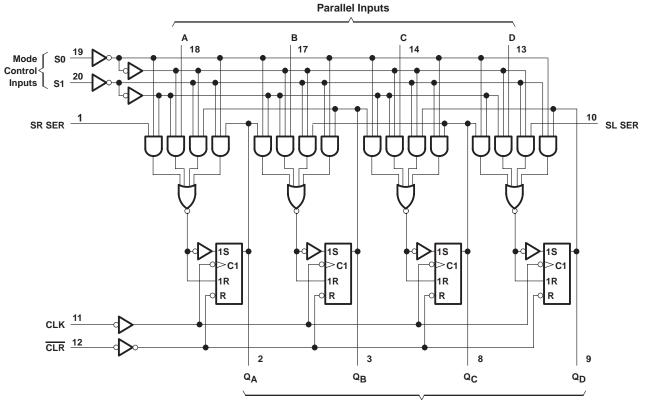


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logic symbol[†]



logic diagram (positive logic)



Parallel Outputs



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	$\dots \dots -0.5$ V to 7 V
Input voltage range, V _I (see Note 1)	$\dots \dots \dots -0.5$ V to V _{CC} + 0.5 V
Output voltage range, VO (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	$\dots \dots \pm 50 \text{ mA}$
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	$\dots \dots \pm 50 \text{ mA}$
Continuous current through V _{CC} or GND pins	± 100 mA
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

			MIN	NOM	MAX	UNIT	
VCC	Supply voltage		3	5	5.5	V	
		V _{CC} = 3 V	2.1				
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			V	
		V _{CC} = 5.5 V	3.85				
		$V_{CC} = 3 V$			0.9		
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35	V	
		V _{CC} = 5.5 V			1.65		
		$V_{CC} = 3 V$			-4		
ЮН	High-level output current	$V_{CC} = 4.5 V$			-24	4 mA	
		V _{CC} = 5.5 V			-24		
		$V_{CC} = 3 V$			12		
lol	Low-level output current	V _{CC} = 4.5 V			24	mA	
		V _{CC} = 5.5 V			24		
VI	Input voltage		0		VCC	V	
VO	Output voltage		0		VCC	V	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V	
TA	Operating free-air temperature		- 40		85	°C	

recommended operating conditions



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		V	T,	ק = 25°C	;			
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		
	l _{OH} = – 50 μA	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
VOH	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		V
		4.5 V	3.94			3.8		
	I _{OH} = – 24 mA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
		3 V			0.1		0.1	
	l _{OL} = 50 μA	4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36		0.44	V
		4.5 V			0.36		0.44	
	I _{OL} = 24 mA	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lj	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	5.5 V			8		80	μA
Ci	$V_{I} = V_{CC}$ or GND	5 V		4				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	DADAM	5750	1	T _A = 25°C		MIN	MAY		
	PARAMETER				MAX	MIN	MAX	UNIT	
fclock	Clock frequency			0	90	0	90	MHz	
		CLK high		5.5		5.5			
t _W Pulse duration	CLK low		5.5		5.5		ns		
		CLR low		4.5		4.5			
		Select		5		5			
t _{su}	Setup time before CLK ↑	Data		4		4		ns	
		Select		1.5		1.5			
th	Hold time after CLK ↑	Data		0.5		0.5		ns	
t	Recovery time			1		1		ns	



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timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	54544		T _A =	T _A = 25°C			
	PARAMETER			MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	100	0	100	MHz
		CLK high	5		5		
t _W Pulse duration	CLK low	5		5		ns	
		CLR low	4.5		4.5		
		Select	4	4 4			
t _{su}	Setup time before CLK \uparrow	Data	2.5		2.5		ns
		Select	1.5		1.5		
t _h H	Hold time after CLK \uparrow	Data	1		1		ns
t	Recovery time		1		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	Т	₄ = 25°C	;	MIN	MAY	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX		MAX	UNIT
fmax			90	120		90		MHz
^t PHL		Amu 0	1	5.8	8.4	1	9.5	
^t PLH	CLK	Any Q	1	6.6	8.9	1	10.2	ns
^t PHL	CLR	Any Q	1.7	7.1	9.5	1.7	10.7	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

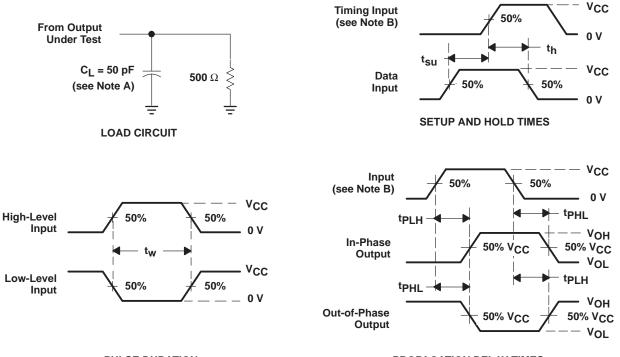
	FROM	то	Τį	ן = 25°C	;	MIN	МАХ	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN		UNIT
f _{max}			100	130		100		MHz
^t PHL	OLK.	Amu O	0.8	3.9	6.2	0.8	6.8	
^t PLH	CLK	Any Q	1.1	4.4	6.6	1.1	7.7	ns
^t PHL	CLR	Any Q	1.5	4.6	7	1.5	7.8	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Po	ower dissipation capacitance	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	66	pF



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PARAMETER MEASUREMENT INFORMATION

PULSE DURATION

PROPAGATION DELAY TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Input pulses are supplied by generators having the following characteristics: $PRR \le 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$. For testing fmax and pulse duration: $t_r = 1$ to 3 ns, $t_f = 1$ to 3 ns.
 - C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC11194DW	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
74AC11194N	OBSOLETE	PDIP	Ν	20	TBD	Call TI	Call TI
74AC11194N	OBSOLETE	PDIP	Ν	20	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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